V1.0



## N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V} \,$

#### **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

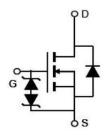
F	ea	tı	ır	۵۵
	-	LL	41	

- New technology for high voltage device
- ●Low on-resistance and low conduction losses
- ●Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Aı	aa	lica	itio	n
	~~			••

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V <sub>DS min@Tjmax</sub>	710	V
R <sub>DS(ON)TYP</sub> .	190	mΩ
$I_D$	17	Α
Qg	19	nC



**Schematic diagram** 

#### **Package Marking And Ordering Information**

Device	Device Package	Marking
NCE65N230K	TO-252	NCE65N230K



TO-252

Table 1. Absolute Maximum Ratings (T<sub>C</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> =0V)	VDS	650	V
Gate-Source Voltage (VDS=0V) ,AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) ,DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	17	A
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	11.9	А
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	51	A
Maximum Power Dissipation(Tc=25℃)	P <sub>D</sub>	172	W
Derate above 25°C		1.15	W/°C
Single pulse avalanche current (Note 2)	I <sub>AS</sub>	3.5	A
Reverse diode dv/dt, $V_{DS} \leq 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	15	V/ns
Drain Source voltage slope,V <sub>DS</sub> ≤480 V	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	$T_{J},T_{STG}$	-55+175	°C



#### **Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	0.87	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states				•		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250uA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125°C)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			100	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±200	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250uA$	3	3.5	4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =8.5A		190	230	mΩ
Dynamic Characteristics						
Gate Resistance	Rg	F=1MHZ, D-S short		18		Ω
Input Capacitance	C <sub>lss</sub>	\/ F0\/\/ 0\/		930	1100	pF
Output Capacitance	Coss	$V_{DS}=50V, V_{GS}=0V,$		50		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1MHz		2		pF
Total Gate Charge	Qg			19		nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =400 $V$ , $I_{D}$ =8.5 $A$ ,		5.0		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V		6.2		nC
Gate plateau voltage	Vgp			5.6		V
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>			10		nS
Turn-on Rise Time	tr	$V_{DD}$ =400 $V$ , $I_{D}$ =8.5 $A$ ,		8		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G$ =4 $\Omega$ , $V_{GS}$ =10 $V$		56		nS
Turn-Off Fall Time	t <sub>f</sub>			10		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T -05°0			17	Α
Pulsed-Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			51	Α
Forward on voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =17A,V <sub>GS</sub> =0V		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			245		nS
Reverse Recovery Charge	Q <sub>rr</sub>	Tj=25°C,I <sub>F</sub> =8.5A <b>,</b>		2.205		uC
Peak reverse recovery current	I <sub>rrm</sub>	di/dt=100A/µs		18		Α

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25  $^{\circ}\text{C}$  ,VDD=50V,VG=10V, RG=25 $\Omega$ 



#### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Output characteristics

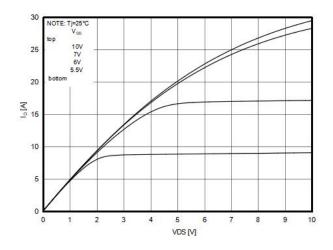


Figure 2. Transfer characteristics

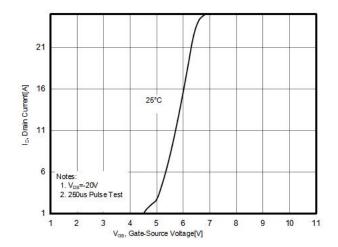


Figure 3. R<sub>DS(ON)</sub> vs Junction Temperature

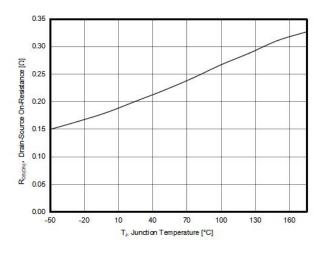


Figure 4. BV<sub>DSS</sub> vs Junction Temperature

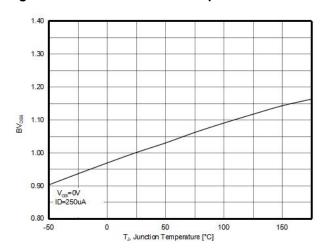


Figure 5. Maximum ID vs Junction Temperature

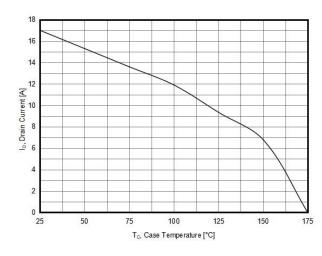
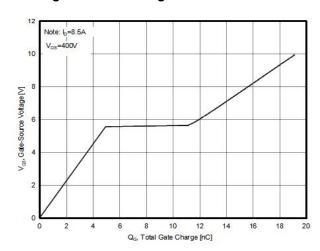


Figure 6. Gate charge waveforms



Wuxi NCE Power Co., Ltd Page 3 http://www.ncepower.com V1.0



Figure 7. Static drain-source on resistance

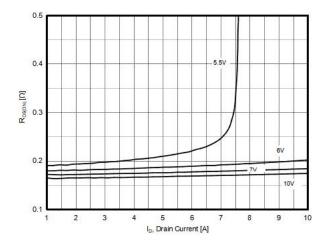


Figure9. Capacitance

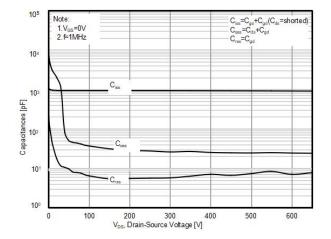


Figure8. Source-Drain Diode Forward Voltage

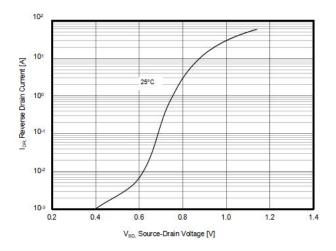
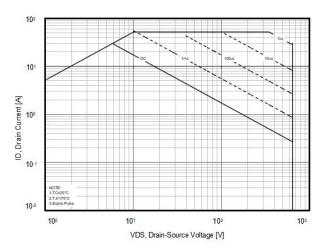


Figure 10. Safe operating area

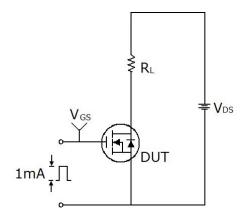


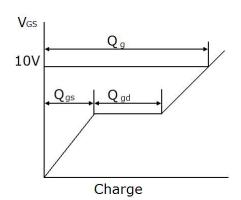
V1.0



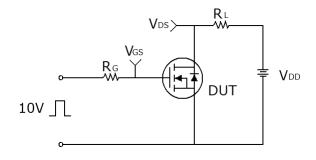
### **Test circuit**

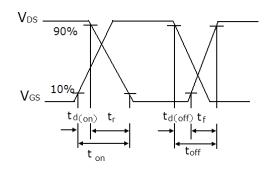
#### 1) Gate charge test circuit & Waveform



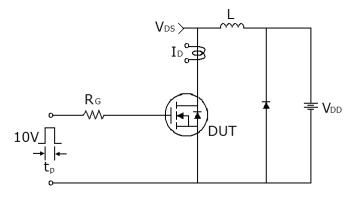


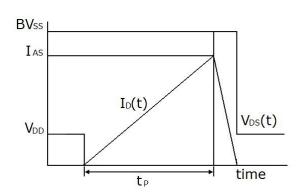
#### 2) Switch Time Test Circuit:





#### 3) Unclamped Inductive Switching Test Circuit & Waveforms

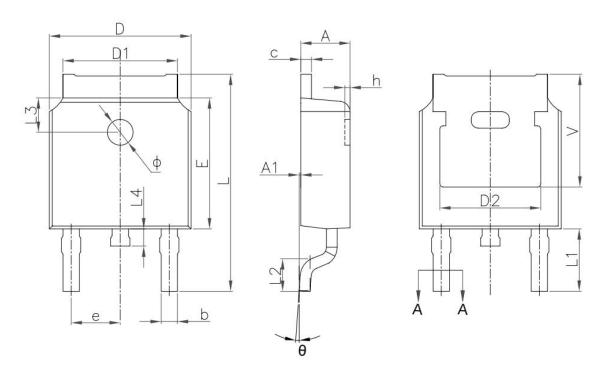




V1.0



# **TO-252 (E) Package Information**



Symbol	Dimensions	In Millimeters	Dimension	s In Inches	
	Min.	Max.	Min.	Max.	
Α	2.20	2.40	0.087	0.094	
A1	0.00	0.13	0.000	0.005	
b	0.66	0.86	0.026	0.033	
b1	0.73	0.79	0.029	0.031	
С	0.46	0.58	0.018	0.023	
c1	0.50	0.52	0.020	0.020	
D	6.50	6.70	0.256	0.264	
D1	5.10	5.46	0.201	0.215	
D2	4.83	3 REF	0.19REF		
E	6.00	6.20	0.236	0.244	
е	2.19	2.39	0.086	0.094	
L	9.80	10.40	0.386	0.409	
L1	2.90 REF		0.11REF		
L2	1.40	1.70	0.055		
L3	1.60	1.60 REF		REF	
L4	0.60	1.00	0.024	0.039	
Ф	1.10	1.30	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.00	0.30	0.000	0.012	



#### ATTENTION:

- Any and all NCE products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your NCE representative nearest you before using any NCE products described or contained herein in such applications.
- NCE assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all NCE products described or contained herein.
- Specifications of any and all NCE products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- NCE Power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all NCE products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of NCE Power Semiconductor CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. NCE believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the NCE product that you intend to use.
- This catalog provides information as of Mar. 2010. Specifications and information herein are subject to change without notice.